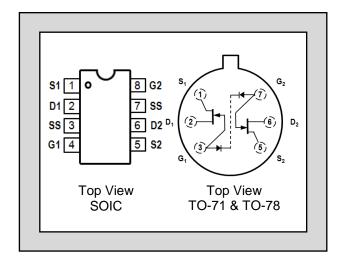


Twenty-Five Years Of Quality Through Innovation

LS830 LS831 LS832 LS833

ULTRA LOW LEAKAGE LOW DRIFT MONOLITHIC DUAL N-CHANNEL JFET AMPLIFIER

FEATURES								
ULTRA LO	OW DRIFT	ΔV _{GS1-2} /Δ	$\Delta V_{GS1-2}/\Delta T$ = 5 μ V/ $^{\circ}$ C max.					
ULTRA LO	DW NOISE	I _G =80fA TY	I _G =80fA TYP.					
LOW NOIS	SE	e _n =70nV/√Hz TYP.						
LOW CAP	ACITANCE	C _{ISS} =3pf max.						
ABSOLUTE MAXIMUM RATINGS NOTE 1								
@ 25°C (unless otherwise noted)								
Maximum Temperatures								
Storage T	-55 to +150°C							
Operating	-55 to +150°C							
Maximum Voltage and Current for Each Transistor NOTE 1								
-V _{GSS}	Gate Voltage to Drain	40V						
-V _{DSO}	Drain to Source Volta	40V						
-I _{G(f)}	Gate Forward Curren	10mA						
-l _G	Gate Reverse Curren	10μΑ						
Maximum Power Dissipation @ TA = 25°C								
Continuo	500mW							

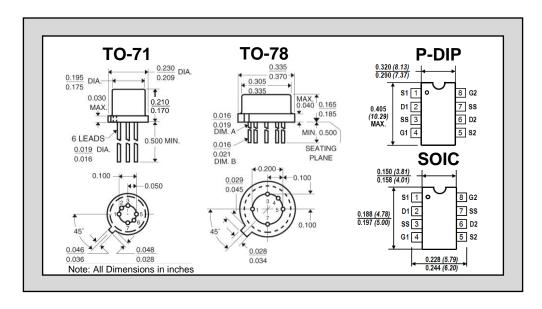


SYMBOL	CHARACTERISTIC	MIN.	TYP.	MAX.	UNITS	CONDITIONS		
BV _{GSS}	Breakdown Voltage	-40	-60		V	V _{DS} = 0	I _G = -1nA	
BV _{GGO}	Gate-to-Gate Breakdown	±40			V	I _G = ±1μΑ	$I_D=0$	Is = 0
	TRANSCONDUCTANCE							
G fss	Full Conduction	70	300	500	μS	V _{DG} = 10V	V _{GS} = 0	f = 1kHz
g fs	Typical Operation	50	100	200	μS	V _{DG} = 10V	I _D = 30µA	f = 1kHz
gfs1-2/gfs	Differential		1	5	%			
	DRAIN CURRENT							
I _{DSS}	Full Conduction	60	400	1000	μΑ			
IDSS1-2/IDSS	Differential at Full Conduction		2	5	%	V _{DG} = 10V	V _{GS} = 0	

ELECTRICAL CHARACTERISTICS TA = 25°C (unless otherwise noted)

SYMBOL	CHARACTERISTIC	LS830	LS831	LS832	LS833	UNITS	CONDITIONS	
$ \Delta V_{GS1-2}/\Delta T $ max.	Drift vs. Temperature	5	10	20	75	μV/ºC	$V_{DG} = 10V$	I _D = 30μA
							$T_A = -55^{\circ}C$ to $+125^{\circ}C$	
V _{GS1-2} max.	Offset Voltage	25	25	25	25	mV	$V_{DG} = 10V$	$I_D = 30\mu A$
-I _G typical	Operating	0.1	0.1	0.1	0.5	pА		
-I _G typical	High Temperature	0.1	0.1	0.1	0.5	nA	TA= +125°C	
I _{GSS} typical	At Full Conduction	0.2	0.2	0.2	1.0	pА	V _{GS} = 20V, V _{GS} = 0V	
I _{GSS} typical	High Temperature	0.5	0.5	0.5	1.0	nA	V _{GS} = 0	V _{GS} = 20V
							TA= +125°C	

SYMBOL	CHARACTERISTIC	MIN.	TYP.	MAX.	UNITS	CONDITIONS		
	GATE-SOURCE							
V _{GS} (off)	Cutoff Voltage	-0.6	-2	-4.5	V	$V_{DS} = 10V$	$I_D=1nA$	
V _G S	Operating Range			-4	V	V _{DG} = 10V	I _D = 30μA	
	GATE CURRENT							
Iggo	Gate-to-Gate Leakage		1		pА	$V_{GG} = \pm 20V$	$I_D = I_S = 0A$	
	OUTPUT CONDUCTANCE							
goss	Full Conduction			5	μS	V_{DG} = 10 V	$V_{GS} = 0$	
gos	Operating			0.5	μS	V _{DG} = 10V	I _D = 30μA	
g os 1-2	Differential			0.1	μS			
	COMMON MODE REJECTION							
CMRR	-20 log ΔV _{GS1-2} / ΔV _{DS}		90		dB	ΔV_{DS} = 10 to 20V I _D =30µ		I _D =30µA
CMRR	-20 log ΔV _{GS1-2} / ΔV _{DS}		90		dB	$\Delta V_{DS} = 5 \text{ to } 10V$		I _D =30μA
	<u>NOISE</u>							
NF	Figure			1	dB	$V_{DS} = 10V$	$V_{GS} = 0$	R_G =10 $M\Omega$
						f= 100Hz	NBW= 6Hz	
e _n	Voltage		20	70	nV/√Hz	V _{DG} = 10V	I _D = 30μA	f= 10Hz
						NBW= 1Hz		
	<u>CAPACITANCE</u>							
C _{ISS}	Input			3	pF	$V_{DS} = 10V$	$V_{GS}=0$	f= 1MHz
Crss	Reverse Transfer			1.5	pF	V _{DS} = 10V	V _{GS} = 0	f= 1MHz
C _{DD}	Drain-to-Drain			0.1	pF	V _{DG} = 10V	I _D = 30μA	



NOTES:

1. These ratings are limiting values above which the serviceability of any semiconductor may be impaired

Information furnished by Linear Integrated Systems is believed to be accurate and reliable. However, no responsibility is assumed for its use; nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Linear Integrated Systems.

Linear Integrated Systems (LIS) is a 25-year-old, third-generation precision semiconductor company providing high-quality discrete components. Expertise brought to LIS is based on processes and products developed at Amelco, Union Carbide, Intersil and Micro Power Systems by company President John H. Hall. Hall, a protégé of Silicon Valley legend Dr. Jean Hoerni, was the director of IC Development at Union Carbide, Co-Founder and Vice President of R&D at Intersil, and Founder/President of Micro Power Systems.